

Global 3D TSV Package Market Research Report 2023

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Abstracts

Currently, 3D Packaging using Through Silicon Via technology (3D TSV) is one of the hottest topics in the semiconductor ecosystem. 3D TSV is vertical electrical connection (via) passing completely through a silicon wafer or die. These short vertical interconnects are replacing the long interconnects of 2D packaging technologies including wire-bond and flip chips.

According to QYResearch's new survey, global 3D TSV Package market is projected to reach US\$ 1475.8 million in 2029, increasing from US\$ 863 million in 2022, with the CAGR of 8.0% during the period of 2023 to 2029. Influencing issues, such as economy environments, COVID-19 and Russia-Ukraine War, have led to great market fluctuations in the past few years and are considered comprehensively in the whole 3D TSV Package market research.

The global market for semiconductor was estimated at US\$ 579 billion in the year 2022, is projected to US\$ 790 billion by 2029, growing at a CAGR of 6% during the forecast period. Although some major categories are still double-digit year-over-year growth in 2022, led by Analog with 20.76%, Sensor with 16.31%, and Logic with 14.46% growth, Memory declined with 12.64% year over year. The microprocessor (MPU) and microcontroller (MCU) segments will experience stagnant growth due to weak shipments and investment in notebooks, computers, and standard desktops. In the current market scenario, the growing popularity of IoT-based electronics is stimulating the need for powerful processors and controllers. Hybrid MPUs and MCUs provide real-time embedded processing and control for the topmost IoT-based applications, resulting in significant market growth. The Analog IC segment is expected to grow gradually, while demand from the networking and communications industries is limited. Few of the emerging trends in the growing demand for Analog integrated circuits include signal conversion, automotive-specific Analog applications, and power management. They drive the growing demand for discrete power devices.

Report Scope

This report, based on historical analysis (2018-2022) and forecast calculation (2023-2029), aims to help readers to get a comprehensive understanding of global 3D TSV Package market with multiple angles, which provides sufficient supports to readers' strategy and decision making.

By Company

Amkor Technology

Jiangsu Changjiang Electronics Technology

Toshiba Electronics

Samsung Electronics

Taiwan Semiconductor Manufacturing Company

United Microelectronics Corporation

Xilinx

Teledyne DALSA

Tezzaron Semiconductor Corporation

Segment by Type

Via-First

Via-Middle

Via-Last

Segment by Application

Logic and Memory Devices

MEMS and Sensors

Power and Analog Components

Other

Production by Region

North America

Europe

China

Japan

South Korea

Consumption by Region

North America

United States

Canada

Europe

Germany

France

U.K.

Italy

Russia

Asia-Pacific

China

Japan

South Korea

China Taiwan

Southeast Asia

India

Latin America, Middle East & Africa

Mexico

Brazil

Turkey

GCC Countries

The 3D TSV Package report covers below items:

Chapter 1: Product Basic Information (Definition, type and application)

Chapter 2: Manufacturers' Competition Patterns

Chapter 3: Production Region Distribution and Analysis

Chapter 4: Country Level Sales Analysis

Chapter 5: Product Type Analysis

Chapter 6: Product Application Analysis

Chapter 7: Manufacturers' Outline

Chapter 8: Industry Chain, Market Channel and Customer Analysis

Chapter 9: Market Opportunities and Challenges

Chapter 10: Market Conclusions

Chapter 11: Research Methodology and Data Source

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 - 1.2.3 Via-Middle
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